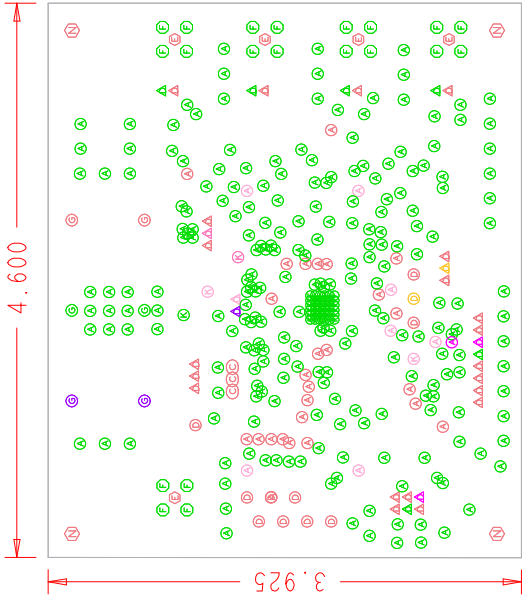


PHYSICAL BOARD DIMENSIONS
& LAYER STRUCTURE

	SILK TOP	silkt.art
	MASK TOP	smaskt.art
	(TOP) COMPONENT	layer1.art
.019	LAYER 2	layer2.art
.019	LAYER 3	layer3.art
.019	(BOTTOM) SOLDER	layer4.art
	MASK BOTTOM	smaskb.art
	SILK BOTTOM	silkb.art

0.019" IS APPROXIMATE CALCULATE 50 OHMS IMPEDANCE OF
14 MIL TRACES REFERENCED TO THE CLOSEST PLANE
.030" IS FPR ISOLATION



DRILL

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	
Ⓐ	10.0	PLATED	260	
Ⓑ	11.0	PLATED	36	
Ⓒ	35.0	PLATED	3	
Ⓓ	40.0	PLATED	11	
Ⓐ	41.0	PLATED	33	
Ⓑ	59.0	PLATED	5	
Ⓓ	67.0	PLATED	20	
Ⓒ	72.0	PLATED	6	
Ⓒ	100.0	PLATED	4	
Ⓐ	128.0	NON-PLATED	4	

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (DIELECTRIC CONSTANT 4.5), 1 OZ COPPER.
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840. CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED ISL74420SEHALIZA IPC356.IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
10. TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
11. ALL 11 MIL VIA'S ARE TO BE THERMAL EPOXY FILLED AND CAPPED.

Drawn By: Tim Klemann	Date Drawn: 02/01/2023	Engineer: Ross Kerley
Released By:	Date Released:	ISL74420EH EVALUATION BOARD LAYOUT
Updated By:	Date Updated:	MASK# HOUR ID REV A
intersil		FILENAME: ~/ISL74420SEH/ISL74420SEHALIZA SHEET 1 of 1